

CLAIMS

1. A method of controlling contact load in an apparatus for mounting electronic components on a substrate, in which a head is lowered at high speed to a slow down starting position where there is no risk that the electronic component makes contact with the substrate (S1), and from there the head is lowered at low speed until a predetermined target contact load is detected, wherein

the process of lowering the head at low speed includes the steps of moving down the head a predetermined distance (S3), measuring load after the step of moving down the head (S5), and determining whether the measured load has reached the target contact load (S9), the steps of moving down the head (S3) and measuring the load (S5) being repeated until the measured load reaches the predetermined target contact load.

2. The method of controlling contact load in an apparatus for mounting electronic components according to claim 1, wherein

the head is stopped for a set period of time after moving down the head (S3) and before measuring load (S5).

3. The method of controlling contact load in an apparatus for mounting electronic components according to claim 1, wherein

the distance by which the head is moved down in the step of moving down the head (S3) is set variably in accordance with the target contact load.

4. The method of controlling contact load in an apparatus for

mounting electronic components according to claim 1, wherein

the moving distance in the step of moving down the head (s3) is set at a first predetermined distance when the measured load is zero (s2) , and is set at a second predetermined distance after
5 the load has exceeded zero (s7) , the second predetermined distance being smaller than the first predetermined distance.

5 . The method of controlling contact load in an apparatus for mounting electronic components according to claim 4, wherein

the second predetermined distance is set variably in
10 accordance with a difference between the measured load and the target contact load.

6 . The method of controlling contact load in an apparatus for mounting electronic components according to claim 1, wherein

when, after the load has exceeded zero, the measured load is
15 the same as the previously measured one in the step of measuring load (s5) , the step of measuring load (s5) is repeated until a different load is detected.